PCN Number:	20230816000.1	PCN Date:	August 17, 2023
Title:	Qualification of alternate mount compound material for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	Nov 14, 2023	Sample Requests accepted until:	Sept 16, 2023*

***Sample requests received after Sept 16, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of an alternate mound compound material set for the list of devices in the product affected sections below.

What	Current	Additional
Die attach material	**4224819/4223872**	**4221460 + 4226215**

Reason for Change:

Standardization

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

SN1205066PDQNR	TLV70727PDQNR	TLV70736PDQNT	TLV71729PDQNT
SN1206013PDQNR	TLV70727PDQNT	TLV717185PDQNR	TLV71733PDQNR
TLV70712PDQNR	TLV707285DQNR	TLV717185PDQNT	TLV71733PDQNT
TLV70712PDQNT	TLV707285DQNT	TLV71718PDQNR	TLV74010PDQNR
TLV70718PDQNT	TLV707285PDQNR	TLV71718PDQNT	TLV74012PDQNR

TLV70719PDQNR	TLV707285PDQNT	TLV71727PDQNR	TLV74018PDQNR
TLV70719PDQNT	TLV70732DQNR	TLV71727PDQNT	TLV74028PDQNR
TLV70725PDQNR	TLV70732DQNT	TLV71729PDQNR	TLV74033PDQNR
TLV70725PDQNT			

Qualification Report

xQFN Offload Into CDAT - DQN (CMOS9T5V)
Approve Date 25-April-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LP5907SNX-3.0/NOPB	QBS Reference: TLV70732DQNR	QBS Reference: LP8556TMX-E09/S1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/915/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity

- Qual Device LP5907SNX-3.0/NOPB is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2111-019

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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